

**Version with Markings to Show Changes Made:**

In the Title:

Please amend the title as follows:

MICROBEAM ASSEMBLY [AND ASSOCIATED METHOD] FOR INTEGRATED  
CIRCUIT INTERCONNECTION TO SUBSTRATES

In the Specification:

Please add the following paragraph on page 1, between the title and "BACKGROUND OF THE INVENTION":

--CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a divisional of U.S. Application No. 09/383,720 filed August 26, 1999, which is hereby incorporated in its entirety by reference.--

In the Claims:

Please cancel original Claims 1-24.

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